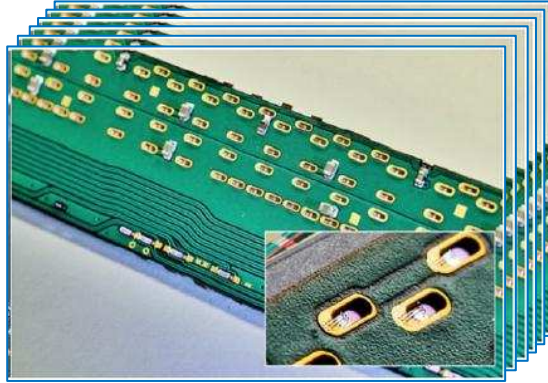


chip test

FPC test



HIC assembly

HIC characterization

CP and SF characterization

for OB: PB characterization

Stave assembly

Stave characterization



Half layer assembly

Half layer characterization

Half barrel assembly

Half barrel characterization

Installation

commissioning

